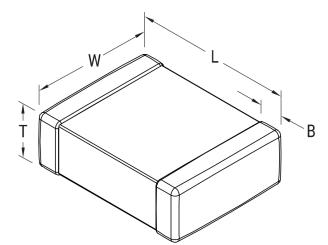


CKC21C104JWGAC7210

KC-LINK Comm COG, Ceramic, 0.1 uF, 5%, 650 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2220



Click here for the 3D model.

Dimensions	
Chip Size	2220
L	5.9mm +/-0.4mm
W	5mm +/-0.4mm
Т	2.5mm +/-0.20mm
В	0.6mm +/-0.35mm

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	2000	
Packaging Quantity	2000	

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	320 mg
Shelf Life	78 Weeks
MSL	1

Specifications				
Capacitance	0.1 uF			
Measurement Condition	1 kHz 1.0Vrms			
Capacitance Tolerance	5%			
Voltage DC	650 VDC			
Dielectric Withstanding Voltage	845 VDC			
Temperature Range	-55/+150°C			
Temperature Coefficient	COG			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms			
Dissipation Factor	0.1% 1 kHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour			
Insulation Resistance	10 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.